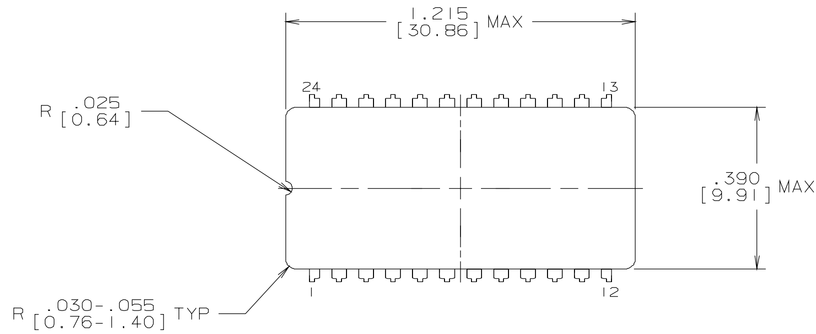
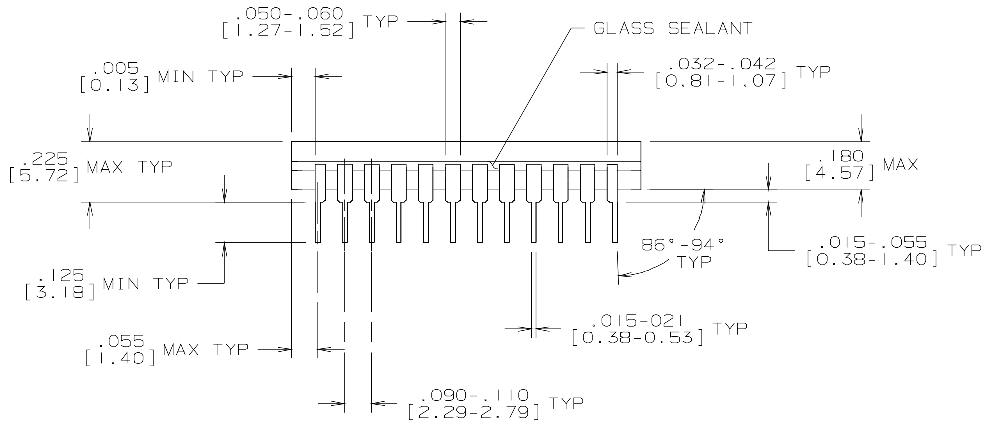
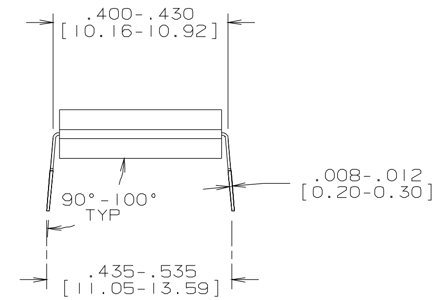
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
J	REVISE AND REDRAW	09044	03/05/92	DEG/







NOTES: UNLESS OTHERWISE SPECIFIED

1. LEAD FINISH: SOLDER DIPPED WITH Sn60 OR Sn63 SOLDER CONFORMING TO MIL-M-38510 TO A MINIMUM THICKNESS OF 200 MICROINCHES/5.08 MICROMETERS. SOLDER MAY BE APPLIED OVER LEAD BASIS METAL OR Sn PLATE.
2. LEAD THICKNESS MAY BE INCREASED BY .003 [0.08] MAXIMUM AFTER LEAD FINISH APPLIED.
3. BUMPERS ARE AVAILABLE ON CERTAIN PRODUCTS. BUMPERS WILL ADD .040 [1.02] MAX TO THE LENGTH OF THE PACKAGE.
4. NO JEDEC REGISTRATION AS OF 2/17/92.

MIL/AERO CONFIGURATION CONTROL

MIL-M-38510 CONFIGURATION CONTROL

CONTROLLING DIMENSION: INCH

APPROVALS	DATE	
DRAWN D.E.GRADY	03/05/92	NATIONAL SEMICONDUCTOR CORPORATION 2900 Semiconductor Drive, Santa Clara, CA 95052-8090
DFTG. CHK.		CERDIP (J), 24 LEAD, .400 CENTERS
ENGR. CHK.		
APPROVAL		

PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
INCH / MM	N/A	C	MKT-J24E	J
	FORMERLY: N/A		SHEET 1 OF 1	